MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SSOP28
CASE 565BD
ISSUE O

DATE 31 DEC 2016

NOTES:
A. CONFORMS TO JEDEC REGISTRATION MO-150,
   VARIATION AH.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH,
   AND TIE BAR EXTRUSIONS.

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